

Быстродействующие черенковские детекторы для триггерной и времяпролетной систем супердетектора АЛИСЕ Большого адронного коллайдера ЦЕРН

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- Experiment ALICE
- Cherenkov Detector T0
- LHC injectors upgrade during LS2 (2019 2020)
   Impact on ALICE detectors
- Concept and functionality of FIT
- Performance of the prototypes

– Cherenkov radiator + MCP-PMT

Conclusion

## Эксперименты на LHC

ФИАН, 2017

## Эксперименты на LHC



## **Filling scheme**



# **The present ALICE detector**



### Current V0

- V0 consists of two arrays of 32 scintillating counters
  - Installed on opposite sides of IP
  - Scintillators coupled to PMTs by fibers  $-3.7 < \eta < -1.7$ , 2.8 <  $\eta < 5.1$

Time resolutions of about 450 ps and 350 ps are achieved for VO-A and VO-C **Current T0** 



- T0 consists of two arrays, placed on the opposite sides of the IP
- Cherenkov radiators, each coupled to PMTs (12 per module)
- -5 < η < -4.5, 2.9 < η < 3.3

Time resolution of ~ 40ps for protons and ~25ps for PbPb collisions

VO & TO Provide triggers, luminosity monitoring, background reduction, collision time (for PID), centrality, and event plane determinations

# **Design considerations**

- detectors on both sides of the interaction point
- compact design (minimal space on RB 26 side)
- time resolution of **about 50 ps**;
- position resolution (along the beam direction) ≈ 1 cm;
- laser calibration system;
- total dead time of less than 25 ns;
- maximum rate (bunch crossing) of **40 MHz**;
- operation in the magnetic field of **up to 0.5 Tesla**;
- radiation hardness up to 500 krad;
- reasonable multiplicity resolution for charged particles.

## **TO-C & TO-A production**



#### WORKING ON TO DETECTOR



## **Detector performance**



**Figure 1** shows the time distribution of (TOA-TOC)/2 after slewing and vertex correction. The time resolution of the TO detector is ~ 25 ps

**Figure 2** shows the time distribution of the summed arrival times inTOA and TOC (interaction time) in Pb-Pb collisions at  $\sqrt{S_{NN}} = 2.76$  TeV.

# **Detector performance**



Figure 3 : Background rejection by TO

**Figure 4** : T0 vertex trigger efficiency during Pb-Pb runs at  $Vs_{NN} = 2,76$  TeV for central and semi-central events (0-50%)

## Luminosity monitoring by T0 trigger signal (OTVX)



Luminosity determination in ALICE at the LHC is based on visible cross sections measured in van der Meer (vdM) scans. The visible cross section is seenby a given detector (or set of detectors) with a given trigger condition is a fraction of the total inelastic interaction cross section.

### Measurement of the event collision time for particle identification via the time-of- flight technique





In pp collisions, for very low multiplicity events, the current T0 detector can provide a  $t_{ev}$  measurement with an efficiency of the order of 70% that increases with the track multiplicity. At the same time, for all events having high multiplicity, the  $t^{TOF}_{ev}$  method is able to provide a  $t_{ev}$  measurement.



## **ALICE PID**



03/07/2012

Pb Vs<sub>NN</sub>=2.76 TeV

p (GeV/c)



ITS standalone tracker, PID (pT<200MeV) – energy loss in the silicon;



#### HMPID Cherenkov angle measurement PID p\_T 1 -5 GeV/c



**TPC** main tracking system PID - energy loss in the gas pT 0.1-1GeV/c



#### TRD

Electron and hadron identification via TR + energy loss in the gas ; pT>1GeV/c

### TOF

0.5

1.5 2 2.5

TOF

0.9

0.8

0.7

0.6

0.5

ALI-PERF-27125

resolution ~85 ps (Pb-Pb); π-k separation up to 2.5GeV/c; protons-4GeV/c



*Elp* from calorimeters (EMCAL, PHOS) Electron identification

### PID (pT<200MeV) – energy the silicon;



# LHC injectors upgrade ( (After the Long Shutdown 2019-2020)

Increase in luminosity

LHC target luminosity *Pb-Pb*  $L = 6 \times 10^{27} \text{ cm}^{-2} \text{s}^{-1}$ corresponding to collision rates of 50 kHz and >200 kHz for pp and p-Pb

 25 ns bunch spacing option for RUN3 and RUN4



# Upgrade Strategy for ALICE at High Rate



- Physics plans focused on rare processes where ALICE is unique
  - Low-pT heavy-flavour mesons and baryons
  - Low-pT charmonia (J/ $\psi$  and  $\psi$  (2S))
  - Low-mass dileptons
- Rate limits of current setup (500 Hz of Pb-Pb events)
- Detector upgrades
- New readout and trigger system

## The Future : ALICE upgrade Program



#### New Inner Tracking System (ITS)

- improved pointing precision
- less material -> thinnest tracker at the LHC

#### Muon Forward Tracker (MFT)

- new Si tracker
- Improved MUON pointing precision

### **MUON ARM**

continuous readout
 electronics

#### **Time Projection Chamber (TPC)**

- new GEM technology for readout chambers
- continuous readout
- faster readout electronics

### New Central Trigger Processor

Data Acquisition (DAQ)/ High Level Trigger (HLT)

- new architecture
- on line tracking & data compression
- 50kHz Pb-Pb event rate

TOF, TRD

• Faster readout

New Trigger Detectors (FIT) (c) by St. Rossegger



## Fast Interaction Trigger replaces 3 detectors in ALICE: T0, V0, and FMD





https://cds.cern.ch/record/781854/files/lhcc-2004-025.pdf

https://cds.cern.ch/record/1603472/files/ALICE-TDR-015.pdf

FIT will consist of two arrays of Cherenkov radiators with MCP-PMT sensors (T0+) and of a single, large-size scintillator ring (V0+)
(FIT = T0+ and V0+ for ALICE after LS2)







- Luminosity monitoring & feedback to LHC
  - Essential for the operation of ALICE
- Fast Interaction Trigger
  - Online Vertex determination
  - Minimum Bias and centrality selection
  - Rejection of beam/gas events
  - Veto for Ultra Peripheral Collisions
- Collision <u>time</u> for Time-Of-Flight particle ID
- Multiplicity → Centrality and Event Plane





## **Prototype of T0+ module**

### PLANACON<sup>®</sup> XP85012 + quartz radiators







MCP-PMT : The MCP-PMT XP85012 with 64 anode pads is transformed into the 4channel photo detector by merging 16 pads (4 × 4) of each cell into a single channel







### The main problems with a Standard PLANACON® XP85012



- 64 individual anodes (sectors) are connected to the common output. The anode MCP capacitance creates inversed (positive) <u>Crosstalk</u> which distorts time measurements when more than one quadrant is hit.
- To collect signals from each quadrant we need to attach an additional PCB. This increases inductance and capacitance of the traces and distorts the shape of the signal. It also makes signal shape **dependent on the coordinates**.
- The total <u>capacitance</u> of the anode system for one quadrant is about 80 pF.
- <u>**Different trace lengths**</u> for individual anodes decrease the MCP time resolution.

## Laser tests of the modified PLANACON



Three quadrants are open to laser pulses. One quadrant is covered.

## **Standard XP85012 Modified**



1 0.0 mV/ 2 0° 50.0 mV/ 2 0°

The leading edge is unstable, depends on charge distribution between individual anodes of the three illuminated quadrants. Oscillation on the trailing edge can be seen. The crosstalk signal is large.

Signals from the 3 illuminated quadrants are stable and without oscillations. The crosstalk signal (on the darkened quadrant) is now ~5x smaller and has only a negative component. There is no time shift. The trailing edge is 1.5x shorter.



### **Our solution** to Modify PLANACON® XP85012



- New PCB for XP85012 was designed and manufactured at <u>Institute of Nuclear Research</u> and assembled to a new PLANACON by Photonis
- The modified PLANACON
  - Eliminated the "positive crosstalk".
  - Increased signal amplitude for a given MCP gain\*
  - Eliminated additional PCB
  - Reduced the size of the unit
  - Improved time resolution and signal shape stability

## Beam tests of the modified PLANACON Standard XP85012 Modified



### As measured in June 2015 Standard XP85012

- MCP amplification 10<sup>6</sup>
- Amplitude ~1100 channels
- Time resolution ~30 ps



### As measured in October 2015 Modified XP85012

- MCP amplification 10<sup>6</sup>
- Amplitude ~2100 channels
- Time resolution ~22 ps

### Radiator granularity results (October 2015 data)





Results for the **repaired NBI MCP** with different combinations of fragmented radiators. 4MCP1-radiator- 1/4 4MCP2-radiators 4/16 new 4MCP4-radiators 16/64 4MCP3-radiator 1/4



**Conclusion** - Reproducible results for quadrants with default radiators (#1, #3) comparing to June 2015 data.

- No benefit in further segmentation of radiators;
- Best timing for 4 default radiators;
- -Perfect pulse shape and largest amplitude for 4 default radiators;

## As measured in June 2016 beam test

**Amplitude vs impact angle of MIPs** 



If T0+ at side C is flat, particles would hit the radiators under the corners of up to **12.6°**.

### For some reason **amplitude decreases with the impact angle of MIPS increase** even for the central pixel events in the MCP window (no radiators).

Many variable/unknown parameters could act here:

•Q.E. variation for oblique photons;•unclear reflectivity of PhC-window border;

•quartz transparency for VUV-light at short distances, etc.

## **FIT module installed in ALICE**

6

0

PMD

**T**0

FIT



### Conclusions

> During the upcoming Long Shutdown 2 (2019-2020) ALICE is going to upgrade several of the key detectors including the Fast Interaction Trigger (FIT).

≻ FIT will consist of two arrays of T0+ modules (quartz Cherenkov radiators coupled to MCP-PMTs) and one V0+ (segmented scintillator ring).

> T0+ prototype with a modified PLANACON XP85012 sensor routinely achieves  $\Delta T \sim 40$  ps during the tests at ALICE in 2016

> The R&D is currently focused in defining plans for detector integration into ALICE, multichannel readout electronics prototyping and detector module testing performed with the real-life conditions at ALICE. FIT collaboration during PS beam tests ~50 people, 14 institutes, 6 counties





# Thank you for your attention!



## **BACKUP SLIDES**

### Russian participation in the upgrade of ALICE detector Results of 2014 – 2016 and future plans Fast Interaction Trigger FIT

- SMCP1 II 33 rs II 21 ps

SMCP2 || 34 ps || 22 ps

SMCP3 || 34 ps || 22 ps.

5MCP4 8 34 p4 8 22 p4

2000 2500 3000

FIT-TOC and FIT-TOA are very well advanced:

- We have optimized the segmentation quartz radiator
- The vendor for the photo sensor has been chosen
- The optical fibres, signal and HV cables have been chosen and approved
- FIT TO+ prototype has been extensively tested at PS and in the actual location inside ALICE, next to TOA, with the actual LHC beam.
- During FIT Design Review on 16 June 2016 the milestones, cost estimate, man power and budget resources were considered

#### Plans for 2017-2020:

- Development and production of the FIT detector mechanical design for integration within ALICE
- Assembling and testing Cerenkov modules
- Development and production of integrated electronic modules, including elements of FE electronics, trigger and readout electronics

EDR (Engineering Design Review at CERN) FIT-C detector (6/17), FIT-A detector (12/17), Electronics (9/17)

PRR (Production Readiness Review at CERN) Electronics (12/18) Installation and commissioning finalized (12/20)













FIT should be as large as possible within the available space inside ALICE!

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# Standard XP85012 Modified





**Standard** off-the-shelf PLANACON® has a common output and uses non-RF connectors for anode outputs

Modified variant has RF grounded MCP out electrode, reduced anode-ground capacitance, and equalized propagation time from individual anodes to the output connectors.



ФИАН, 2017



POWER GROUND(S)

CATHODE BIAS MCPIN BIAS MCPOUT BIAS

### Modified PLANACON® XP85012 version 2





Reduced size of the HV port, optimized Hv divider placement

Result: Assembled detector module length decreases ~10 mm to 67 mm

MCP plates resistance decreased ~3 times to 16 -17 Mohms

Result:

- Dynamic range increases at least 2 times, now covers FIT requirements.
- All MCP internal time constants are reduced in 3 times.
- 40 MHz burst repetition rate test passed.
- Average 1 MHz interaction rate test to be finished, preliminary passed.
- □ Minor changes of the PCB
  - Result:
  - Electrical crosstalk between quadrants now is less than optical one.



# **FIT configuration T0C+**



Flat  $(R = \infty)$  Concave (R = 80 cm)



The distance between IP and <u>TOC+</u> is only 80 cm Performance of the TO+ module depends on the impact angle of MIPs

### Concave geometry is now possible due to the thinning of the MCP-PMT sensor

## **Importance of V0+**

### FIT simulation results Event plane & centrality resolution



# **New Modified XP85012-V2**

### PHOTONIS

Tube Type:	XP85012/A1-Q - PROTO	
Serial #:	9002059	
Date:	18-Apr-16	

DC	TEST	DATA	

Cathode (white) Cathode (blue)	68 9.9	μA/Im μA/Blm
Overall HV for 10 <sup>5</sup> gain	1505	V
Overall HV for 10 <sup>6</sup> gain	1800	V
I dank (@10 <sup>5</sup> gain)	0.4	nA
I dank (@10 <sup>6</sup> gain)	4	nA
MCP resistance	16	Meg-Ω



\* No Internal Limiting Resistors on HV connections \* Custom Electrode and Signal Connections

#### CAUTION:

* Never Expose to Helium or Hydrogen Gas
* Cathode at Negative High Voltage ONLY.
* Max DC Anode Current = 3µA
* Maximum Overall Voltage Using Test Divider = 2.0 KV
* Maximum MCP Voltage= 1.8 KV

### PHOTONIS

Tube Type:	XP85012/A1-Q - PROTO 9002060	
Serial #:		
Date:	18-Apr-16	

#### DC TEST DATA

Cathode (white) Cathode (blue)	71	µA/Im µA/Blm
Overall HV for 10 <sup>5</sup> gain	1655	V
Overall HV for 10 <sup>6</sup> gain	1590	V
I dank (@10 <sup>5</sup> gain)	0.3	nA
I dank (@10 <sup>6</sup> gain)	4	nA
MCP resistance	16.5	Meg-Ω

#### NOTES:

\* No Internal Limiting Resistors on HV connections \* Custom Electrode and Signal Connections

#### CAUTION:

\* Never Expose to Helium or Hydrogen Gas \* Cathode at Negative High Voltage ONLY. \* Max DC Anode Current = 3µA \* Maximum Overall Voltage Using Test Divider = 2.0 KV \* Maximum MCP Voltage= 1.8 KV



#### TEST VOLTAGE DIVIDER









## **Big progress in MCP technology** (since the initial R&D for ALICE)



- Appearance of <u>commercially available</u> MCP-PMTs (Hamamatsu, Photonis USA, BINP)
- Significant and ongoing <u>improvement in lifetime</u>:



- Modified photocathodes [JINST 6 C12026 (2011)]
- Reduced outgassing (borosilicate glass)

# Lifetime of MCP-PMTs (Nov. 2015)



- Hamamatsu film MCP-PMT: Q.E. drops beyond 1 C/cm<sup>2</sup>
- Photonis 9001332: no Q.E degrading observed yet up to >9 C/cm<sup>2</sup>

MCP-PMTs with ALD layers: very good performance to >5 C/cm<sup>2</sup> Albert Lehmann

DIRC 2015 -- Rauischholzhausen -- November 11, 2015

## Lifetime of MCP-PMTs (Feb. 2016)

![](_page_41_Figure_1.jpeg)

- Hamamatsu film MCP-PMT: Q.E. drops beyond 1 C/cm<sup>2</sup>
- Photonis 9001332: no Q.E degrading observed up to 10 C/cm<sup>2</sup>
- MCP-PMTs with ALD layers: very good performance to >6 C/cm<sup>2</sup>

Albert Lebmann

VCI 2016 -- Vienna (Austria) -- February 17, 2016

### FIT = T0+ and V0+

![](_page_42_Picture_1.jpeg)

![](_page_42_Picture_2.jpeg)

![](_page_42_Picture_3.jpeg)

![](_page_42_Picture_4.jpeg)

### T0+ → modular detector:

- Improved T0
- Rectangular quartz radiators
- New sensors MCP-PMT
- Larger acceptance
- More channels
- Upgraded electronics and readout

### V0+ → sectored detector:

- Improved V0
- Faster plastic scintillator
- Monolithic structure
- Reduced fiber length
- New sensor (SiPM or MCP-PMT)
- New electronics and readout

#### Spectrosil<sup>®</sup> 1000

#### Application:

= Semiconductor industry

#### Characteristics:

- = Highest chemical purity
- = Free of bubbles and inclusions
- = Superior transmission in UV and IR
- = Attractive performance/cost ratio

Spectrosil<sup>®</sup> 1000 synthetic fused silica is manufactured using an environmentally friendly process resulting in a glass of exceptional purity and excellent visual quality.

Spectrosil<sup>®</sup> 1000 has been designed for the highest demanding semiconductor applications. Spectrosil<sup>®</sup> 1000 is chlorine-free, free of bubbles and inclusions, and provides an ultra-high purity which makes it one of the cleanest materials available.

Quartz components made from Spectrosil® 1000 eliminate the risk of contamination in plasma etch applications and sensitive deposition processes such as ALD.

![](_page_43_Picture_11.jpeg)

In addition the superior transmission characteristics make it the ideal material for use in modern UV and IR assisted processes.

Sizes for 300 and 450mm semi-conductor tools available.

Max diameter of round ingots:

- = up to 380 mm direct fused ingots
- = 420 700\* mm reflow ingots

\*Larger sizes available on request

![](_page_43_Figure_18.jpeg)

![](_page_43_Figure_19.jpeg)

#### Sum of Al, Ca, Cu, Fe, Na, K, Li, Mg, Ti in ppb.

## **Quark-Gluon Plasma**

- Quark-Gluon Plasma (QGP): phase of deconfined quarks and gluons
- QGP behaves as a perfect fluid
  - Well described by ideal hydrodynamics
  - Viscosity near quantum lower limit  $(\eta/s > 1/4\pi)$
- Phase transition near 170 MeV
- Crossover or 1<sup>st</sup>-order phase transition between QGP and hadron gas
- Critical point?
  - RHIC Energy Scan

![](_page_44_Figure_9.jpeg)